

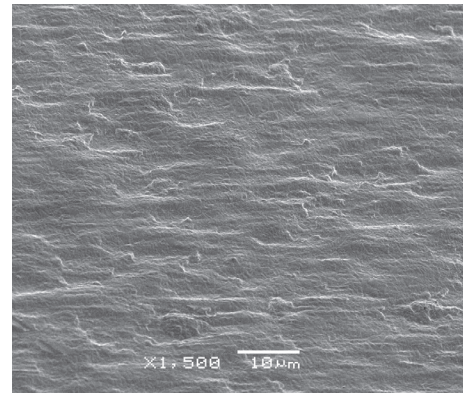
Low profile electrodeposited copper foil.

**Applications:**

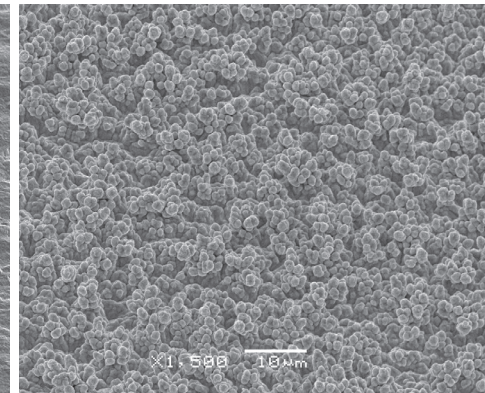
- PCB inner layers

**Features:**

- IPC Grade III
- Treatment on matte side of foil
- Excellent adhesion to a wide range of resin systems



Untreated Drum Side  
H oz. /18 μm (1500x)



Treated Matte Side  
H oz. /18 μm (1500x)

**Typical Values:**

Attribute		Unit	Value				Reference
Thickness Designation			Q	T	H	1	IPC-4562, 1.2.5.1 Table 1-1; IPC-TM-650-2.2.12
Nominal Thickness		μm	9	12	18	35	
		oz.	1/4	3/8	1/2	1	
Area Weight		g/m <sup>2</sup>	75.9	106.8	152.5	305	
		oz./ft <sup>2</sup>	0.25	0.375	0.5	1	
Roughness	Drum Side	μm	0.25				IPC-TM-650-2.2.17
		μ"	10				
	Matte Side	μm	4.5	5.1	5.1	6.4	
		μ"	175	200	200	250	
Tensile	Ambient	Kg/mm <sup>2</sup>	42			38.7	IPC-TM-650-2.4.18
		Kpsi	60			55	
	180°C	Kg/mm <sup>2</sup>	21				
		Kpsi	30				
Elongation	Ambient	%	>3	6	8	15	
	180°C	%	8				
Peel Strength* (Matte/Treated Side)	Cond. B	Kg/cm	>0.89	1.25	1.3	1.9	IPC-TM-650-2.4.8
		Lbs/in	>5.0	7.0	7.5	10.5	

\* Peel strength measured on 170°C Tg Epoxy

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